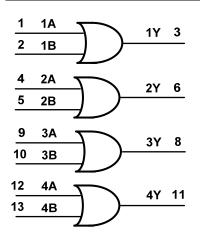


# **Pin Descriptions**

Pin Number	Pin Name	Function
1	1A	Data Input
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	V <sub>CC</sub>	Supply Voltage

# Logic Diagram



# **Function Table**

Inp	Output	
Α	В	Y
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

### Absolute Maximum Ratings (Note 4) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range	-0.5 to +7.0	V
I <sub>IK</sub>	Input Clamp Current VI < -0.5V	-20	mA
I <sub>OK</sub> Output Clamp Current V <sub>O</sub> < -0.5V		-20	mA
I <sub>OK</sub> Output Clamp Current V <sub>O</sub> > V <sub>CC</sub> +0.5V		25	mA
Ι <sub>Ο</sub>	Continuous Output Current $-0.5V < V_0 V_{CC} + 0.5V$	+/- 25	mA
Icc	Continuous Current Through V <sub>CC</sub>	75	mA
I <sub>GND</sub>	Continuous Current Through GND	-75	mA
T <sub>J</sub> Operating Junction Temperature		-40 to +150	°C
T <sub>STG</sub> Storage Temperature		-65 to +150	°C
Ртот	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



## **Recommended Operating Conditions** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage		2.0	5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	Vcc	V
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 3.0V to 3.6V		100	ns/V
ΔυΔν	Input Transition Rise of Fail Rate	V <sub>CC</sub> = 4.5V to 5.5V		20	ns/v
T <sub>A</sub>	Operating Free-Air Temperature		-40	+125	°C

Note: 5. Unused inputs should be held at  $V_{CC}$  or Ground.

Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Sympol	Parameter	Test Conditions	М	T <sub>A</sub> = -40°	C to +85°C	T <sub>A</sub> = -40°C	to +125°C	l ln it
Symbol	Farameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit
		2.0V	1.5		1.5			
VIH	V <sub>IH</sub> High-Level Input Voltage		3.0V	2.1		2.1		V
			5.5V	3.85		3.85		
			2.0V		0.5		0.5	
VIL	VIL Low-Level Input Voltage		3.0V		0.9		0.9	V
			5.5V		1.65		1.65	
	V <sub>OH</sub> High-Level Output Voltage	I <sub>OH</sub> = -50μA	2.0V	1.9		1.9		v
		I <sub>OH</sub> = -50µА	3.0V	2.9		2.9		
V <sub>OH</sub>		I <sub>OH</sub> = -50μA	4.5V	4.4		4.4		
		I <sub>OH</sub> = -4mA	3.0V	2.48		2.40		
		I <sub>OH</sub> = -8mA	4.5V	3.80		3.70		
		I <sub>OL</sub> = 50μA	2.0V		0.1		0.1	
		I <sub>OL</sub> = 50μA	3.0V		0.1		0.1	
V <sub>OL</sub>	V <sub>OL</sub> Low-Level Output Voltage	I <sub>OL</sub> = 50μA	4.5V		0.1		0.1	V
		I <sub>OL</sub> = 4mA	3.0V		0.44		0.55	1
		I <sub>OL</sub> = 8mA	4.5V		0.44		0.55	]
lı	Input Current	V <sub>I</sub> = GND to 5.5V	3.6V		±1		±2	μA
Icc	Supply Current	$V_1$ = GND or $V_{CC}$ , $I_0$ =0	3.6V		20		40	μA

# **Operating Characteristics**

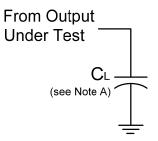
	Parameter	Test Conditions	V <sub>CC</sub> = 2.0V Typ	V <sub>CC</sub> = 3.3V Typ	V <sub>CC</sub> = 5V Typ	Unit
$C_{\text{pd}}$	Power Dissipation Capacitance per Gate	f = 1 MHz	9.7	11.0	14.9	pF
Ci	Input Capacitance	V <sub>i</sub> = V <sub>CC</sub> – or GND	4.0	4.0	4.0	pF



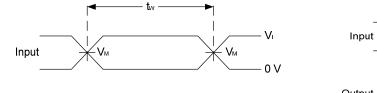
## **Switching Characteristics**

Symbol Parameter		Test		T <sub>A</sub> = +25°C		-40°C to +85°C		-40°C to +125°C		Unit	
Symbol	Falameter	Conditions	Vcc	Min	Тур	Max	Min	Max	Min	Max	Unit
		Figure 1	3.0V to 3.6V	0.5	4.5	7.9	0.5	9.5	0.5	10.0	
	Propagation	C <sub>L</sub> = 15pF	4.5V to 5.5V	0.5	3.2	5.5	0.5	6.5	0.5	7.0	20
t <sub>PD</sub>	Delay $A_N$ to $Y_N$	Figure 1	3.0V to 3.6V	0.5	6.0	11.4	0.5	13.0	0.5	14.5	ns
		$C_L = 50 pF$	4.5V to 5.5V	0.5	4.5	7.5	0.5	8.5	0.5	9.5	

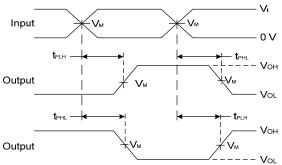
#### **Parameter Measurement Information**



M	Inputs			
Vcc	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	υL
3.3V -3.6V	V <sub>CC</sub>	3ns	V <sub>CC</sub> /2	15pF, 50pF
4.5V to 5.5V	V <sub>CC</sub>	3ns	V <sub>CC</sub> /2	15pF, 50pF



Voltage Waveform Pulse Duration



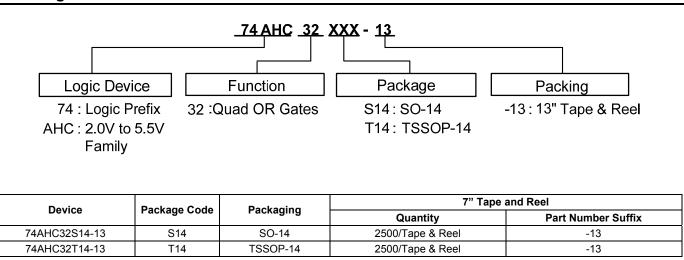
Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

#### Figure 1. Load Circuit and Voltage Waveforms

- Notes: A . Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq$  1 MHz.
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$ .

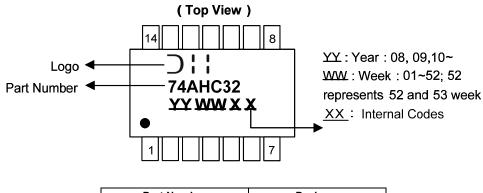


### **Ordering Information**



## **Marking Information**

(1) SO-14, TSSOP-14



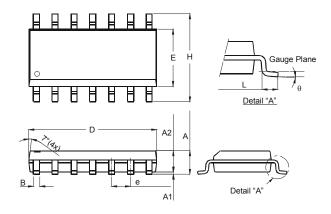
Part Number	Package
74AHC32S14	SO-14
74AHC32T14	TSSOP-14



## Package Outline Dimensions (All dimensions in mm.)

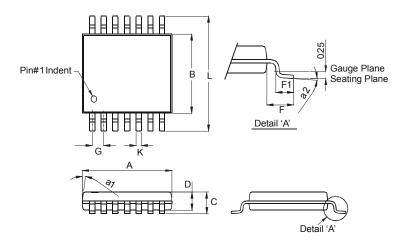
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

#### Package Type: SO-14



	SO-14				
Dim	Min	Max			
Α	1.47	1.73			
A1	0.10	0.25			
A2	1.45	Тур			
В	0.33	0.51			
D	8.53	8.74			
ш	3.80	3.99			
е	1.27	Тур			
H	5.80	6.20			
L	0.38	1.27			
θ	0°	8°			
All Di	mensions	s in mm			

#### Package Type: TSSOP-14



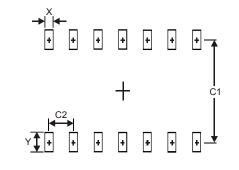
Т	SSOP-1	4	
Dim	Min	Max	
a1	7° (4X)		
a2	0° 8°		
Α	4.9	5.10	
в	4.30	4.50	
С	_	1.2	
D	0.8	1.05	
F	1.00	Тур	
F1	0.45	0.75	
G	0.65	Тур	
κ	0.19	0.30	
L	6.40	Тур	
All D	imensio	ns in	
	mm		



## **Suggested Pad Layout**

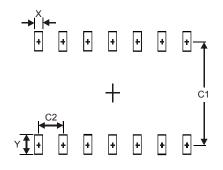
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

#### Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Y	1.50
C1	5.4
C2	1.27

#### Package Type: TSSOP-14



Dimensions	Value (in mm)
Х	0.45
Y	1.45
C1	5.9
C2	0.65



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